74ACT11112 DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOP WITH CLEAR AND PRESET

SCAS064A - D3339, JUNE 1989 - REVISED APRIL 1993

- Inputs Are TTL-Voltage Compatible
- Fully Buffered to Offer Maximum Isolation From External Disturbance
- Flow-Through Architecture Optimizes
 PCB Layout
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

DORNPACKAGE (TOP VIEW) 1PRE 16**|**1 1J 15 1K 1Q [1Q [14 1 1CLK 3 GND [13 1 1 CLR 12 V_{CC} 2<u>Q</u> [5 2Q 6 11 2CLR 2PRE 7 10 2CLK 9**∏** 2K 8 2J [

description

This device contains two independent J-K negative-edge-triggered flip-flops. A low level at the PRE or CLR input sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the fall time of the clock pulse. Following the hold-time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

The 74ACT11112 is characterized for operation from – 40°C to 85°C.

FUNCTION TABLE

INPUTS						PUTS
PRE	CLR	CLK	J	K	Q	Q
L	Н	X	Χ	Х	Н	L
Н	L	X	Χ	X	L	Н
L	L	X	Χ	X	H [†]	H [†]
Н	Н	\downarrow	L	L	Q ₀	\overline{Q}_0
Н	Н	\downarrow	Н	L	Н	L
Н	Н	\downarrow	L	Н	L	Н
Н	Н	\downarrow	Н	Н	TOG	GLE
Н	Н	Н	Χ	Х	Q ₀	\overline{Q}_0

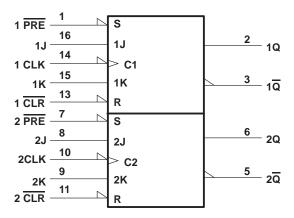
† This configuration is nonstable; that is, it will not persist when either PRE or CLR returns to the inactive (high) level.

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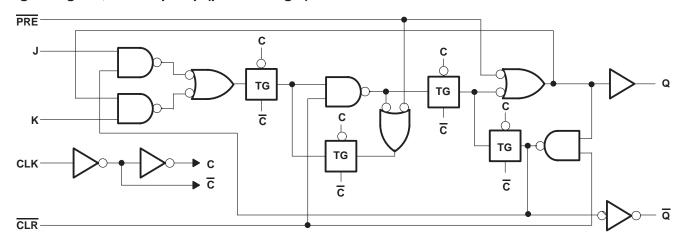
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logic symbol[†]



[†] This symbol is in accordnace with ANSI/IEEE Std 91-1984 and IEC Publication 617-42.

logic diagram, each flip-flop (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, VO (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Storage temperature range	– 65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.



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recommended operating conditions

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
٧o	Output voltage	0	VCC	V
IOH	High-level output current		-24	mA
loL	Low-level output current		24	mA
Δt/Δν	Input transition rise or fall rate	0	10	ns/V
TA	Operating free-air temperature	- 40	85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS	vcc	T _A = 25°C			MIN	MAX	UNIT
PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	IVIIIN	WAX	UNIT
	ΙΟΗ = – 50 μΑ	4.5 V	4.4			4.4		
	10H = - 30 μΑ	5.5 V	5.4			5.4		
Voн	Jour 24 mA	4.5 V	3.94			3.8		V
	$I_{OH} = -24 \text{ mA}$		4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	I _{OL} = 50 μA	4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
VOL	I _{OL} = 24 mA	4.5 V			0.36		0.44	V
	10L = 24 111A				0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
lį	$V_I = V_{CC}$ or GND	5.5 V			± 0.1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			4		40	μΑ
Δl _{CC} ‡	V _I = V _{CC} or GND	5.5 V			0.9		1	mA
Ci	V _I = V _{CC} or GND	5 V		3.5				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			T _A = 1	25°C	MIN	MAX	UNIT
					IVIIIN	IVIAA	UNIT
fclock	Clock frequency			125		125	MHz
	Pulse duration	PRE or CLR low			4		ns
t _W	ruise duration	CLK high or low	4		4		
	Saturations hafara CLK	Data high or low	3.5		4.5		no
t _{su}	Setup time before CLK↓ PRE or CLR inactive		2		2		ns
th	Hold time after CLK↓		1.5		1.5		ns

[‡] This parameter is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

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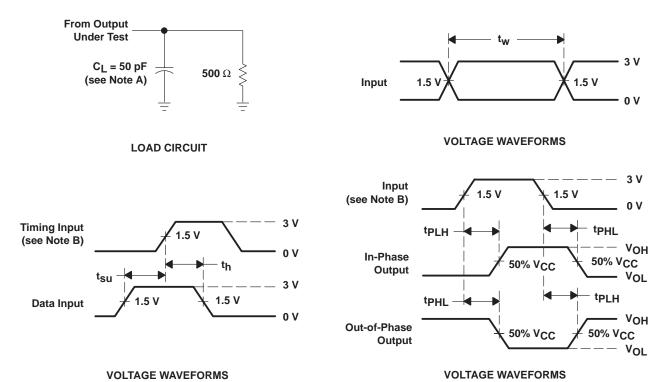
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T _A = 25°C			MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	IVIIIN	WAX	UNIT
f _{max}			125			125		MHz
^t PLH	PRE or CLR	0.04.0	1.5	3.6	6.3	1.5	6.8	ns
^t PHL	PRE OF CLR	Q or Q	1.5	4.6	7.4	1.5	8	115
^t PLH	CLK	0 or 0	1.5	4.2	7	1.5	7.7	ne
tPHL	OLK	Q or Q	1.5	4.7	7.4	1.5	8.4	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	39	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







ti.com 30-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT11112D	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
74ACT11112DR	OBSOLETE	SOIC	D	16	TBD	Call TI	Call TI
74ACT11112N	OBSOLETE	PDIP	N	16	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

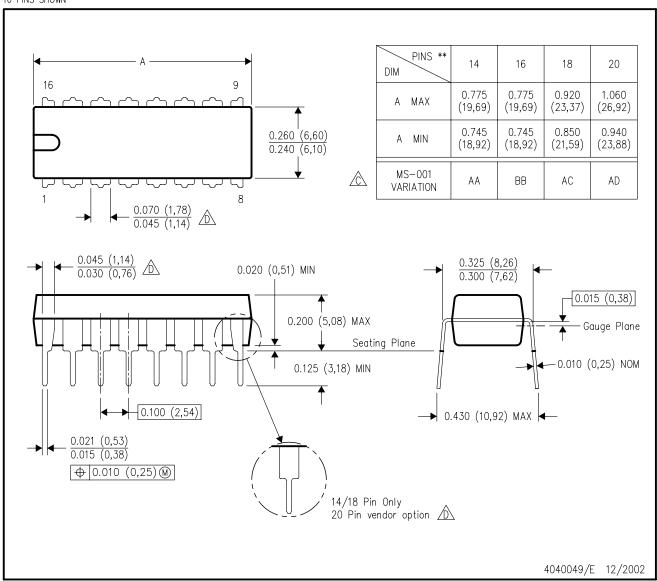
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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



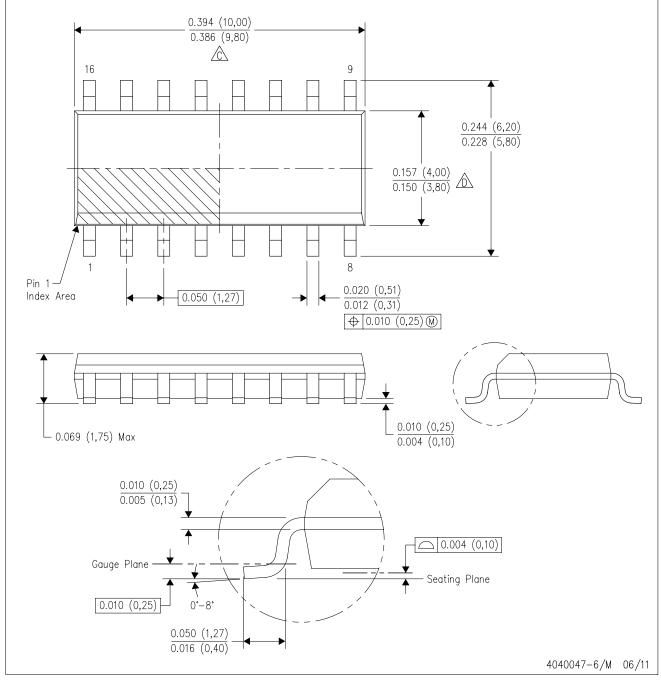
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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